SCES468D - JULY 2003 - REVISED JANUARY 2008

- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- 2-V to 5.5-V V_{CC} Operation
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC}= 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation

description/ordering information

This triple 3-input positive-AND gate is designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV11A performs the Boolean function $Y = A \cdot B \cdot C$ or $Y = \overline{A + B + C}$ in positive logic.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION[†]

T _A	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	TSSOP – PW	Tape and reel	SN74LV11ATPWRQ1	LV11AT

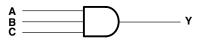
[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

FUNCTION TABLE

[‡] Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

	(each gate)											
	INPUTS	OUTPUT										
Α	В	С	Y									
Н	Н	Н	Н									
L	х	Х	L									
Х	L	Х	L									
х	Х	L	L									

logic diagram, each gate (positive logic)





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PW PACKAGE (TOP VIEW)										
1A 1B 2A 2B 2C 2Y GND	1 2 3 4 5 6 7	Ο	14 13 12 11 10 9 8		V _{CC} 1C 1Y 3C 3B 3A 3Y					

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 5.5 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage		2	5.5	V	
		$V_{CC} = 2 V$	1.5			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$.,	
VIH	High-level input voltage	V _{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		v	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$			
		V _{CC} = 2 V		0.5		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$.,	
V _{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		V		
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		$V_{CC} \times 0.3$		
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	V _{CC}	V	
		$V_{CC} = 2 V$		-50	μA	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		
I _{OH}	High-level output current	V _{CC} = 3 V to 3.6 V		-6	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		
		V _{CC} = 2 V		50	μA	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		
I _{OL}	Low-level output current	V _{CC} = 3 V to 3.6 V		6		
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		12		
		$V_{CC} = 2.3 V \text{ to } 2.7 V$		200		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100	ns/V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		20		
T _A	Operating free-air temperature		-40	105	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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PARAMETER	TEST CONDITIONS	V _{CC}	MIN	ТҮР	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			
.,	$I_{OH} = -2 \text{ mA}$	2.3 V	2			.,
V _{OH}	$I_{OH} = -6 \text{ mA}$	3 V	2.48			v
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
	I _{OL} = 2 mA	2.3 V			0.4	
V _{OL}	I _{OL} = 6 mA	3 V			0.44	v
	I _{OL} = 12 mA	4.5 V			0.55	ν ν μΑ μΑ
l _l	$V_{I} = 5.5 \text{ V or GND}$	0 to 5.5 V			±1	μA
I _{CC}	$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	5.5 V			20	μA
I _{off}	V_1 or $V_0 = 0$ to 5.5 V	0 V			5	μA
Ci	$V_{I} = V_{CC} \text{ or } GND$	3.3 V		1.9		pF

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	₄ = 25°C	;	NAINI		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	UNIT
t _{pd}	A, B, or C	Y	$C_L = 50 \text{ pF}$		9.9	17.5	1	21	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	₄ = 25°C		RAINI	MAX	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	UNIT
t _{pd}	A, B, or C	Y	$C_L = 50 \text{ pF}$		7.2	12.3	1	14	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

P/	DADAMETED	FROM	то	LOAD	T,	₄ = 25°C		NAINI	MAX	
	PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	ТҮР	MAX	MIN	MAX	UNIT
	t _{pd}	A, B, or C	Y	C _L = 50 pF		5.4	7.9	1	9	ns



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noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

	PARAMETER	MIN	ТҮР	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		0	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		3.2		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

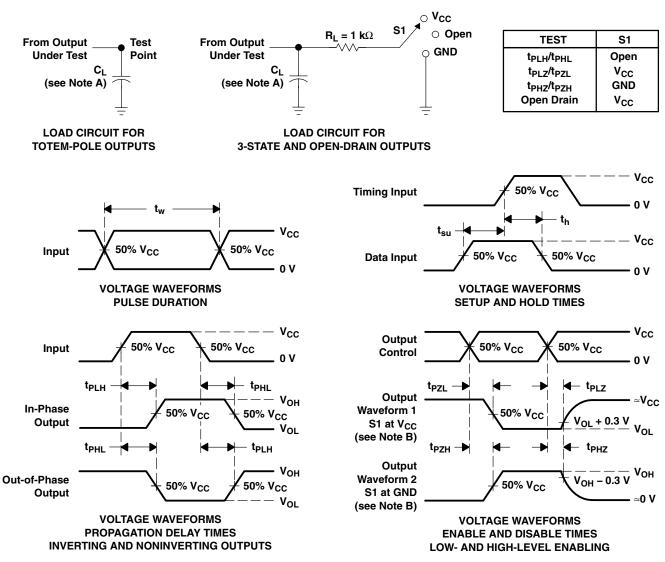
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	V _{CC}	TYP	UNIT
6	Dower dissinction conscitance	C = 50 pc	f = 10 MHz	3.3 V	13.9	pF
Cpd	Power dissipation capacitance	C _L = 50 pF,		5 V	15.4	



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	e Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV11ATPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV11AT	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LV11A-Q1 :



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PACKAGE OPTION ADDENDUM

10-Dec-2020

Catalog: SN74LV11A

• Enhanced Product: SN74LV11A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications



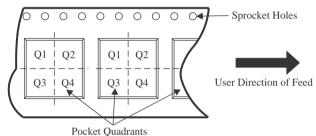
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV11ATPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All	dimensions	are	nominal
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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV11ATPWRG4Q1	TSSOP	PW	14	2000	356.0	356.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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